L	Hits	Search Text	DB	Time stamp
Number				
-	2045	438/613.ccls. 438/411.ccls.	USPAT;	2003/05/15
		438/461.ccls. 438/611.ccls.	EPO; JPO	23:10
	i	257/737.ccls.		
_	956	(438/613.ccls. 438/411.ccls.	USPAT;	2003/05/14
		438/461.ccls. 438/611.ccls.	EPO; JPO	21:05
		257/737.ccls.) and bumps		
_	36	((438/613.ccls. 438/411.ccls.	USPAT;	2003/05/14
		438/461.ccls. 438/611.ccls.	EPO; JPO	21:06
		257/737.ccls.) and bumps) and		
		"thermoplastic resin"		
-	4	(((438/613.ccls. 438/411.ccls.	USPAT;	2003/05/14
		438/461.ccls. 438/611.ccls.	EPO; JPO	21:06
		257/737.ccls.) and bumps) and		
		"thermoplastic resin") and jig		
_	1377	438/613.ccls. 438/411.ccls.	USPAT;	2003/05/15
		438/461.ccls. 438/611.ccls.	EPO; JPO	18:50
		257/737.ccls. and "flip chip"		
-	680	(438/613.ccls. 438/411.ccls.	USPAT;	2003/05/15
		438/461.ccls. 438/611.ccls.	EPO; JPO	18:51
		257/737.ccls. and "flip chip") and bump		
_	14	((438/613.ccls. 438/411.ccls.	USPAT;	2003/05/15
		438/461.ccls. 438/611.ccls.	EPO; JPO	18:57
		257/737.ccls. and "flip chip") and		
		bump) and "base substrate"		
-	0	bumps near "pressed in"	USPAT;	2003/05/15
			EPO; JPO	18:59
-	0	"electrically connecting the bumps"	USPAT;	2003/05/15
			EPO; JPO	19:00
-	375	electric\$4 near connect\$3 near bumps	USPAT;	2003/05/15
			EPO; JPO	19:05
-	0	(electric\$4 near connect\$3 near bumps)	USPAT;	2003/05/15
		same ((one single) adj step)	EPO; JPO	19:10
_	20	(electric\$4 near connect\$3 near bumps)	USPAT;	2003/05/15
		same (sealing adhering)	EPO; JPO	19:10
-	2	("6208525" "5602420").pn.	USPAT	2003/05/15
				23:10
	1	(("6208525" "5602420").pn.) and jig	USPAT	2003/05/15
				23:10